

REMARKS/ARGUMENT

Minor revisions are being made to clarify page 2. The apparatus claims are being cancelled and replaced with a set of method claims 6-19.

EXPRESS MAIL CERTIFICATE

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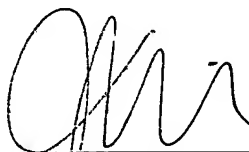


Signature

January 8, 2002

Date of Signature

Respectfully submitted,



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APPENDIX B
VERSION WITH MARKINGS TO SHOW CHANGES MADE
37 C.F.R. §1.121(b)(iii) and (c)(ii)

SPECIFICATION:

Paragraph at page 2, line 9:

After the shielding case 1 is mounted, there are cases where quality-control testing is performed to determine whether circuits on the circuit substrate 4 properly operate according to design specifications. As a result of the testing, if a circuit mounted on the circuit substrate 4 is not working sufficiently because of a defect found in an electronic component electromagnetically shielded in the shielding case 1, a component-replacement process or some other correction [operations] operation (which is referred to as reworking [as follows) are] in the following) is performed. The reworking is performed such that the shielding case 1 is removed, and the defective electronic component is replaced with a new suitable component.

Paragraph at page 2, line 22:

In the reworking, the shielding case 1 is removed in the following steps. First, all [solders] solder joints fixing the leg sections 3 of the shielding case 1 are simultaneously heated and are melted. Then, in the state where all the [solders] solder joints are melted, the cover section 2 is lifted in the direction in which the cover section 2 will be separated from the circuit substrate 4. In this state, the individual leg sections 3 are pulled out through the through-holes 6 provided on the circuit substrate 4. In this way, the shielding case 1 can be removed form the circuit substrate 4.